

#### **General Description**

The WSD3056DN is the highest performance trench Dual N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSD3056DN meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

#### **Features**

Advanced high cell density Trench technology

Super Low Gate Charge

Excellent CdV/dt effect decline

100% EAS Guaranteed

Green Device Available

#### **Product Summery**

Bvdss	Rdson	ΙD
30V	13mΩ	35A

#### **Applications**

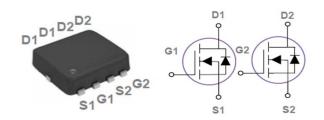
**POL Applications** 

MB / VGA / Vcore

Load Switch

SMPS 2nd SR

#### **DFN3X3 Dual Pin Configuration**



# Absolute Maximum Ratings @TA=25°C unless otherwise noted

Symbol	Parameter		Rating	Units
$V_{ m DS}$	Drain-Source Voltage		30	V
V <sub>GS</sub>	Gate-Source Voltage		±20	V
ΙD	Drain Current (Continuous) *AC	Tc=25°C	35	A
		Tc=100°C	22	
Ідм	Drain Current (Pulse) *B		140	A
PD	Power Dissipation Tc=25°C		27	W
EAS	Single Pulse Avalanche Energy		13	mJ
RθJA	Thermal Resistance Junction to ambient		62	°C/W
Rejc	Thermal Resistance Junction to Case		4.6	°C/W
TJ//TSTG	Operating Temperature/ Storage Temperature		-55~150	$^{\circ}$



## Electrical Characteristics @TA=25°C unless otherwise noted

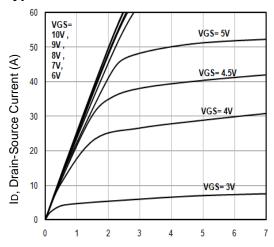
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit			
Static									
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250 \mu A$	30			V			
Idss	Zero Gate Voltage Drain Current	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{V}$			1	μΑ			
Igss	Gate Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			100	nA			
On Characte	On Characteristics								
V <sub>GS(TH)</sub>	Gate Threshold Voltage	$V_{GS}=V_{DS},I_{DS}=250\mu A$	1.0	1.8	2.5	V			
D	Drain-Source On-state Resistance	$V_{GS} = 10V, I_D = 10A$		10	13	mΩ			
RDS(on)		$V_{GS} = 4.5V, I_D = 8A$		14	18	mΩ			
gFS	Forward Transconductance	$V_{DS} = 5V$ , $I_D = 5A$		6		S			
Switching	=			•					
Qg	Total Gate Charge			7.2		nC			
Qgs	Gate-Source Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, I <sub>D</sub> =5A		2.3		nC			
Qgd	Gate-Drain Charge			3		nC			
td (on)	Turn-on Delay Time			3.8		ns			
tr	Turn-on Rise Time	$V_{GS}$ =10V, $V_{DD}$ =15V, $I_{D}$ =1A, $R_{G}$ =6 $\Omega$		10		ns			
td(off)	Turn-off Delay Time			22		ns			
tf	Turn-off Fall Time			6.6		ns			
Rg	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz		2.8		Ω			
Dynamic		<u>'</u>		•					
Ciss	Input Capacitance			620		pF			
Coss	Output Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz		85		pF			
Crss	Reverse Transfer Capacitance			30		pF			
Drain-Source	Drain-Source Diode Characteristics and Maximum Ratings								
Is	Continuous Source Current	~			35	A			
Isм	Pulsed Source Current3	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			70	A			
$V_{\mathrm{SD}}$	Diode Forward Voltage	$I_{SD} = 1A$ , $V_{GS} = 0V$			1.2	V			

#### Note:

- 1, Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2, VDD=25V,VGS=10V,L=0.1mH,IAS=16A.,RG=25 ,Starting TJ=25  $^{\circ}$ C.
- 3. The data tested by pulsed, pulse width  $\leq 300$ us, duty cycle  $\leq 2\%$ .
- 4. Essentially independent of operating temperature.



## **Typical Characteristics**



VDS, Drain -Source Voltage (V)

Fig1. Typical Output Characteristics

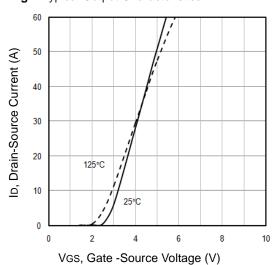


Fig3. Typical Transfer Characteristics

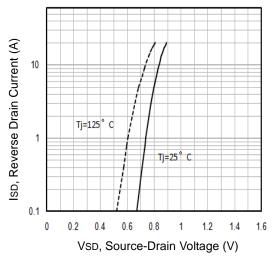


Fig5. Typical Source-Drain Diode Forward Voltage

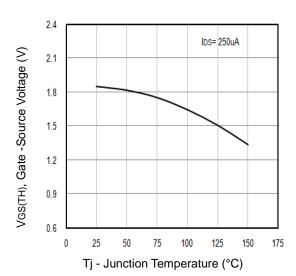


Fig2. Threshold Voltage Vs. Temperature

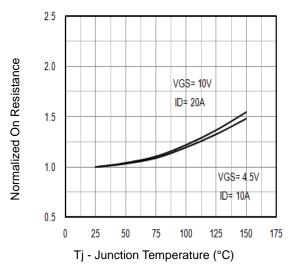
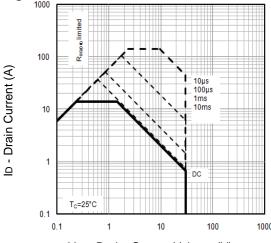


Fig4. Normalized On-Resistance Vs. Temperature



VDS, Drain -Source Voltage (V)

Fig6. Maximum Safe Operating Area



# **Typical Characteristics**

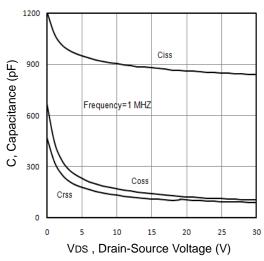


Fig7. Typical Capacitance Vs.Drain-Source Voltage

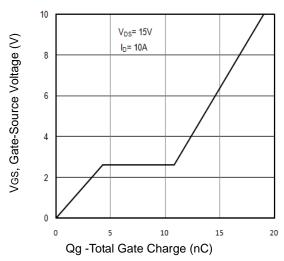
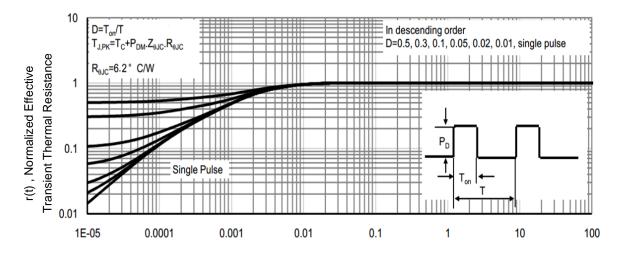
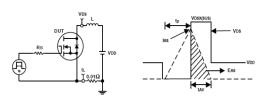


Fig8. Typical Gate Charge Vs.Gate-Source Voltage



T1, Square Wave Pulse Duration(sec)

Fig9. T1 ,Transient Thermal Response Curve



**Fig10.** Unclamped Inductive Test Circuit and waveforms

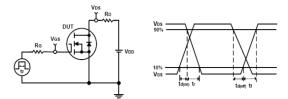
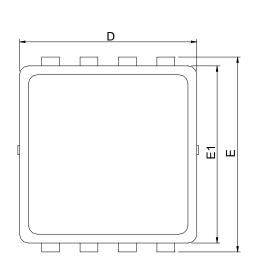
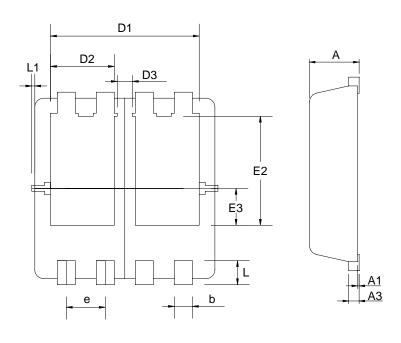


Fig11. Switching Time Test Circuit and waveforms



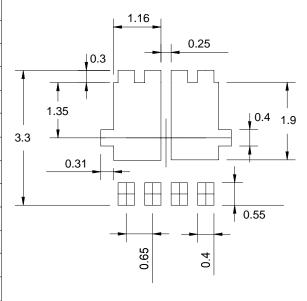
# DFN3x3B-8\_EP2





Ş	DFN3x3-8_EP2				
SY MBOL	MILLIMETERS		INCHES		
<u>۲</u>	MIN.	MAX.	MIN.	MAX.	
Α	0.70	0.90	0.028	0.035	
A1	0.00	0.05	0.000	0.002	
А3	0.10	0.25	0.004	0.010	
b	0.24	0.35	0.009	0.014	
D	2.90	3.10	0.114	0.122	
D1	2.375	2.575	0.094	0.101	
D2	0.963	1.163	0.038	0.046	
D3	0.175	0.275	0.007	0.011	
Е	3.10	3.30	0.122	0.130	
E1	2.90	3.10	0.114	0.122	
E2	1.713	1.913	0.067	0.075	
E3	0.425	0.625	0.017	0.025	
е	0.65 BSC		0.026 BSC		
L	0.30	0.50	0.012	0.020	
L1	0.000	0.100	0.000	0.004	

# **RECOMMENDED LAND PATTERN**



UNIT: mm



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